

**MB05F THRU MB10F SINGLE PHASE
0.8AMP SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER**

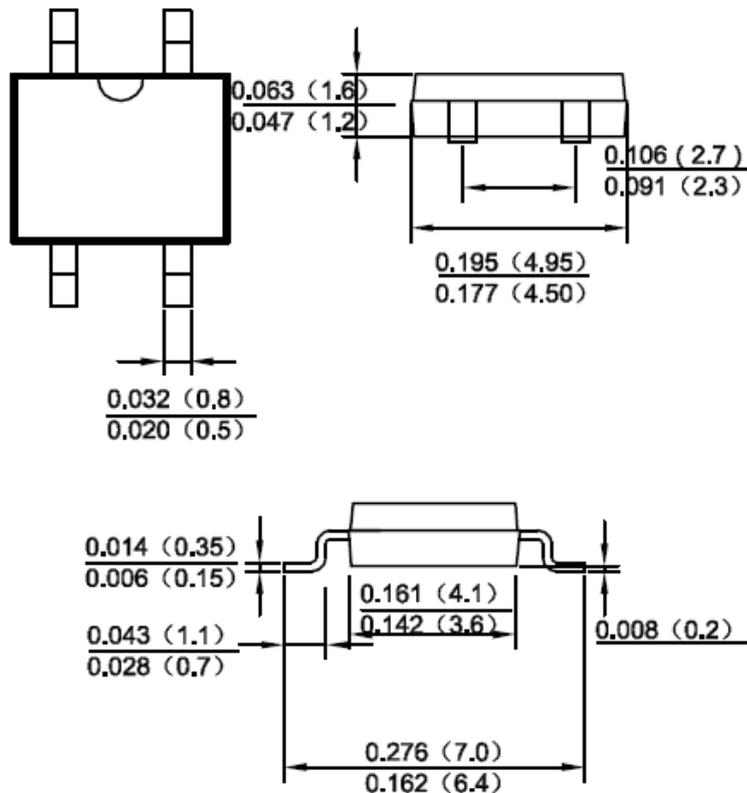
Features:

- Glass passivated die construction
- Low forward voltage drop
- High current capability
- High surge current capability
- Designed for surface mount application
- Plastic material-UL flammability 94V-0

Mechanical Data:

- Case: MB-F, Molded plastic
- Terminals: Plated leads solderable per MIL-STD-202, Method 208
- Polarity: as marked on case
- Mounting Position: Any
- Ordering Information: 5000pcs/reel
- Lead Free: For RoHS / Lead Free Version

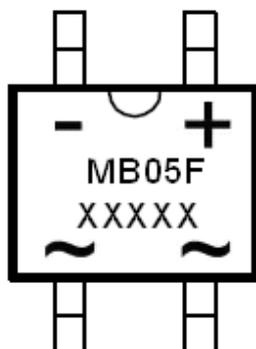
Mechanical Dimensions: In Inches/ mm



MBF

Technical Data
Data Sheet N1456, Rev. A

Marking Diagram:



Where XXXXX is YYWWL

MB05F = Part Name
YY = Year
WW = Week
L = Lot Number

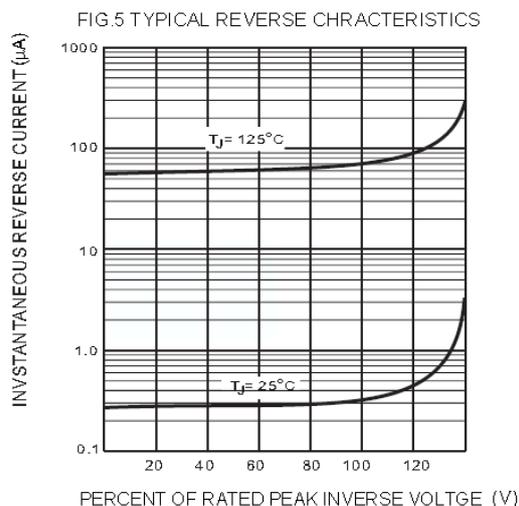
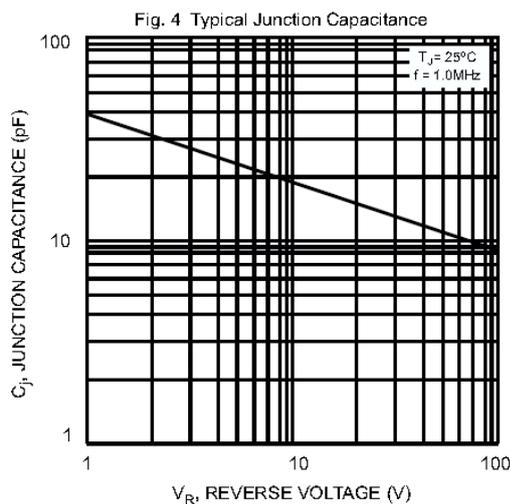
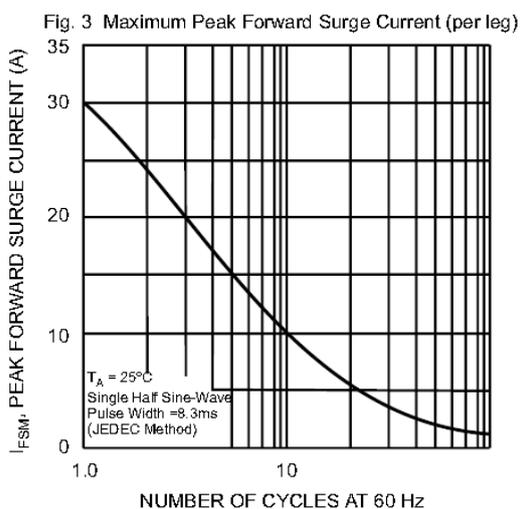
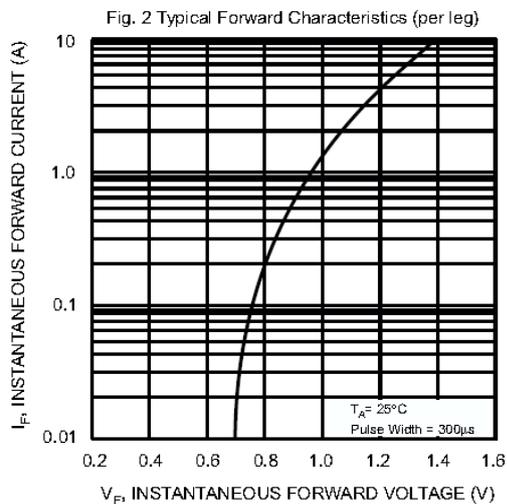
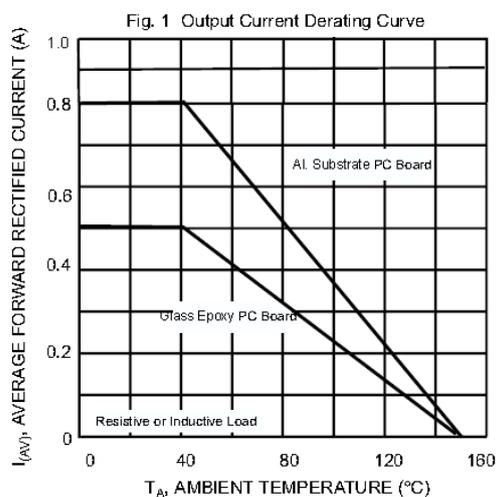
Cautions: Molding resin
Epoxy resin UL:94V-0

Maximum Ratings and Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	MB05F	MB1F	MB2F	MB4F	MB6F	MB8F	MB10F	Unit
Device Marking	Marking	MB05F	MB1F	MB2F	MB4F	MB6F	MB8F	MB10F	-
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	480	700	V
Average Rectified Output Current (Note1)@ $T_A=40^\circ\text{C}$ (Note 2)@ $T_A=40^\circ\text{C}$	I_O	0.5 0.8							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30							A
Forward Voltage per element @ $I_F=0.8\text{A}$	V_{FM}	1.1							V
Peak Reverse Current @ $T_A=25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A=125^\circ\text{C}$	I_R	5 500							μA
Typical Junction Capacitance (Note 3)	C_j	13							pF
Typical Thermal Resistance per leg	$R_{\theta JA}$	60							$^\circ\text{C/W}$
	$R_{\theta JL}$	16							
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55+150							$^\circ\text{C}$

Note: 1. Mounted on glass epoxy PC board with 1.3mm^2 solder pad.
2. Mounted on aluminum substrate PC board with 1.3mm^2 solder pad.
3. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

Technical Data
Data Sheet N1456, Rev. A





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Technical Data
Data Sheet N1456, Rev. A

Green Products

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